

# SWITCHMODE Power Rectifiers

## MBR1240MFS, NRVB1240MFS

### Features

- Low Power Loss / High Efficiency
- New Package Provides Capability of Inspection and Probe After Board Mounting
- Guardring for Stress Protection
- Low Forward Voltage Drop
- 150°C Operating Junction Temperature
- Wettable Flacks Option Available
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices

### Mechanical Characteristics:

- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94-0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL 1 Requirements

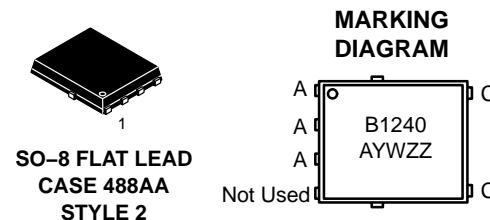
### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	40	V
Average Rectified Forward Current (Rated $V_R$ , $T_C = 140^\circ\text{C}$ )	$I_{F(AV)}$	12	A
Peak Repetitive Forward Current, (Rated $V_R$ , Square Wave, 20 kHz, $T_C = 138^\circ\text{C}$ )	$I_{FRM}$	20	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	150	A
Storage Temperature Range	$T_{stg}$	-65 to +175	°C
Operating Junction Temperature	$T_J$	-55 to +150	°C
Unclamped Inductive Switching Energy (10 mH Inductor, Non-repetitive)	$E_{AS}$	150	mJ
ESD Rating (Human Body Model)		3B	
ESD Rating (Machine Model)		M4	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

NOTE: The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dPD/dT_J < 1/RJA$ .

## SCHOTTKY BARRIER RECTIFIERS 12 AMPERES 40 VOLTS

B1240 = Specific Device Code  
 A = Assembly Location  
 Y = Year  
 W = Work Week  
 ZZ = Lot Traceability

### ORDERING INFORMATION

Device	Package	Shipping†
NRVB1240MFST1G	SO-8 FL (Pb-Free)	1500 / Tape & Reel

### DISCONTINUED (Note 1)

MBR1240MFST1G	SO-8 FL (Pb-Free)	1500 / Tape & Reel
MBR1240MFST3G	SO-8 FL (Pb-Free)	5000 / Tape & Reel
NRVB1240MFST3G	SO-8 FL (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

1. **DISCONTINUED:** These devices are not recommended for new design. Please contact your onsemi representative for information. The most current information on these devices may be available on [www.onsemi.com](http://www.onsemi.com).

# MBR1240MFS, NRVB1240MFS

## THERMAL CHARACTERISTICS

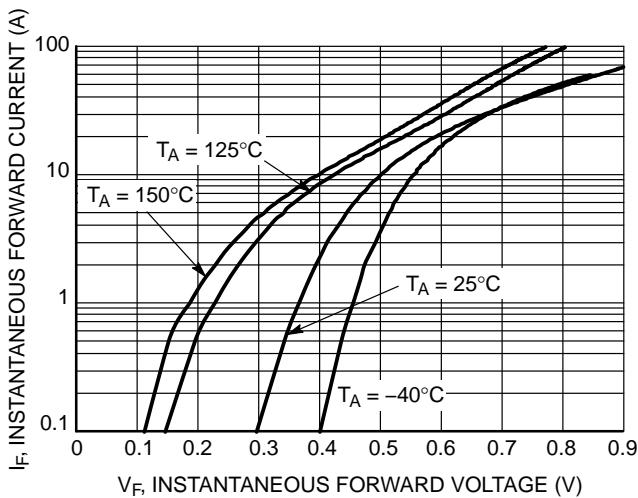
Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance, Junction-to-Case, Steady State (Assumes 600 mm <sup>2</sup> 1 oz. copper bond pad, on a FR4 board)	R <sub>θJC</sub>	—	1.7	°C/W

## ELECTRICAL CHARACTERISTICS

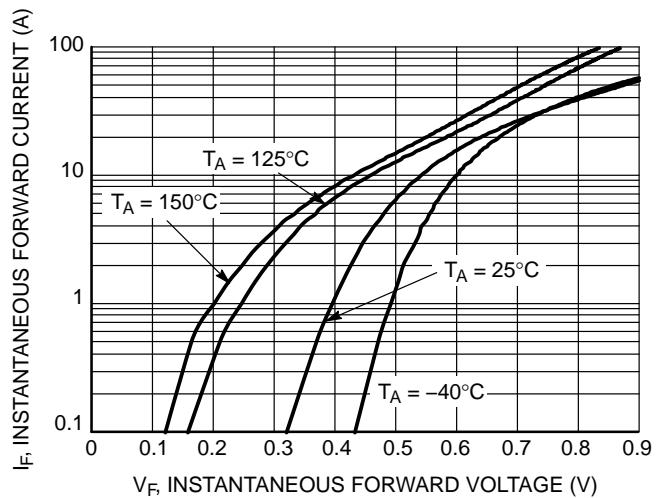
Instantaneous Forward Voltage (Note 1) (i <sub>F</sub> = 12 A, T <sub>J</sub> = 125°C) (i <sub>F</sub> = 12 A, T <sub>J</sub> = 25°C)	v <sub>F</sub>	0.455 0.53	0.62 0.68	V
Instantaneous Reverse Current (Note 1) (Rated dc Voltage, T <sub>J</sub> = 125°C) (Rated dc Voltage, T <sub>J</sub> = 25°C)	i <sub>R</sub>	35 0.08	170 0.5	mA

1. Pulse Test: Pulse Width = 300 µs, Duty Cycle ≤ 2.0%.

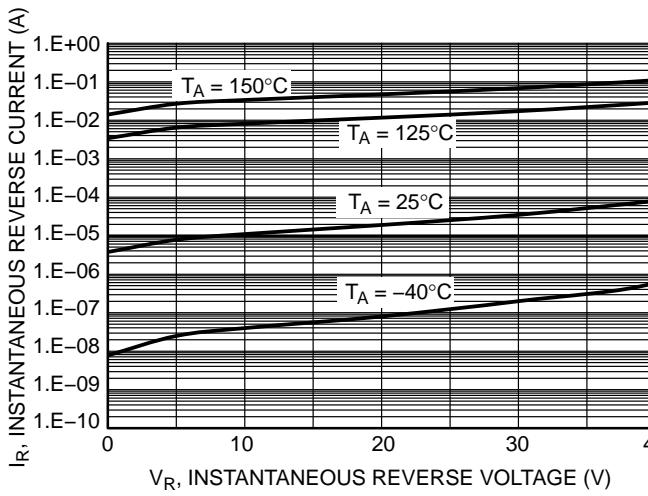
**TYPICAL CHARACTERISTICS**



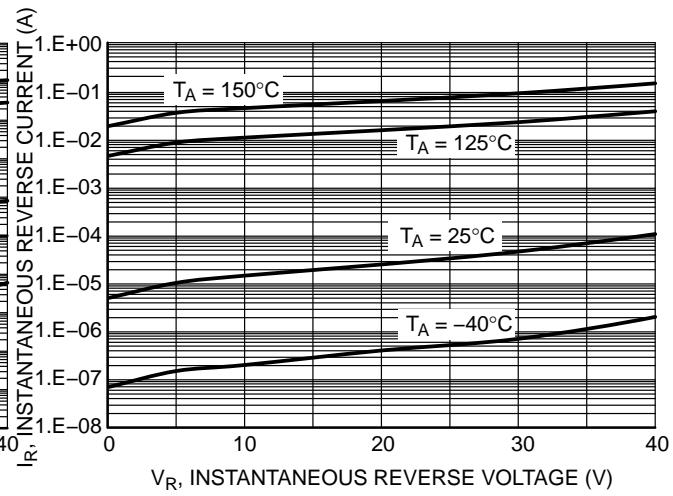
**Figure 1. Typical Instantaneous Forward Characteristics**



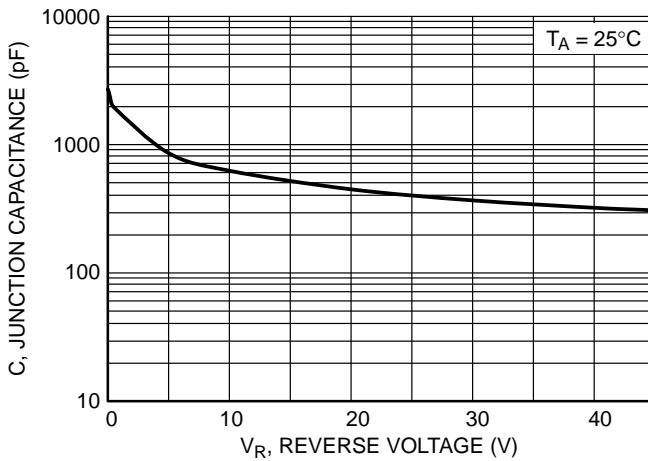
**Figure 2. Maximum Instantaneous Forward Characteristics**



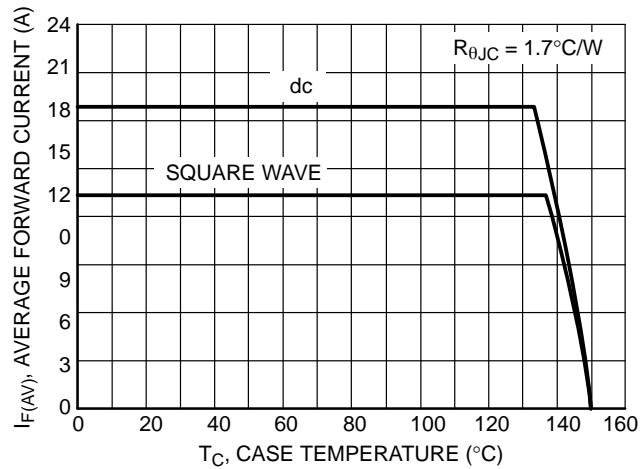
**Figure 3. Typical Reverse Characteristics**



**Figure 4. Maximum Reverse Characteristics**



**Figure 5. Typical Junction Characteristics**



**Figure 6. Current Derating TO-220AB**

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## TYPICAL CHARACTERISTICS

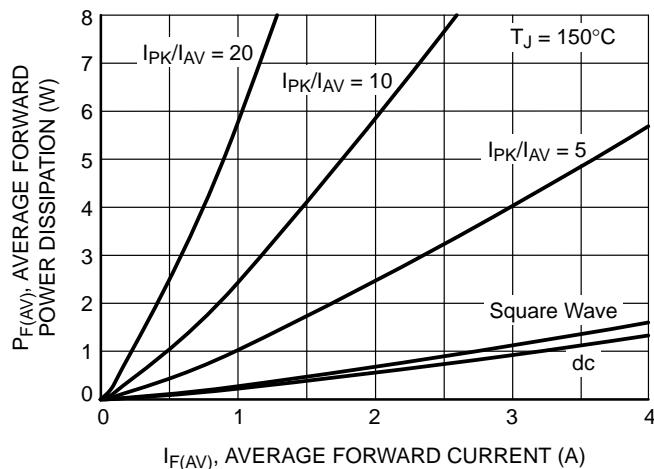


Figure 7. Forward Power Dissipation

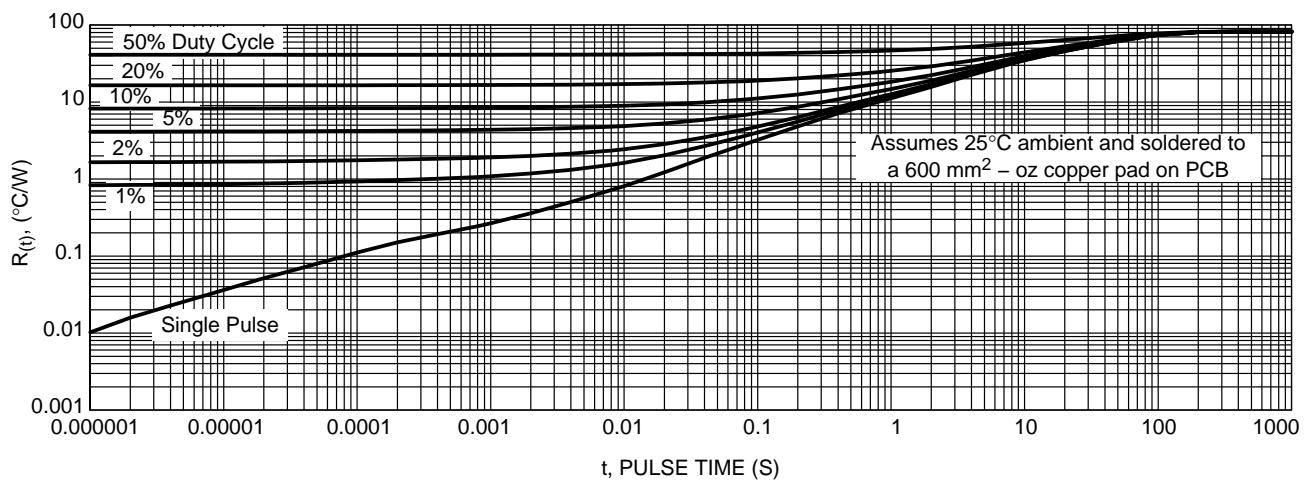
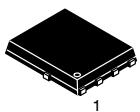


Figure 8.  $R_{(t)}$  vs. Duty



SCALE 2:1

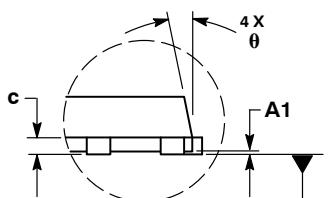
DFN5 5x6, 1.27P  
(SO-8FL)  
CASE 488AA  
ISSUE N

DATE 25 JUN 2018

## NOTES:

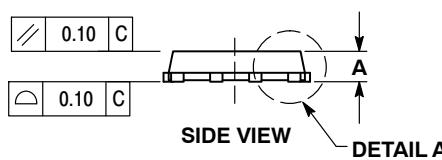
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	---	0.05
b	0.33	0.41	0.51
c	0.23	0.28	0.33
D	5.00	5.15	5.30
D1	4.70	4.90	5.10
D2	3.80	4.00	4.20
E	6.00	6.15	6.30
E1	5.70	5.90	6.10
E2	3.45	3.65	3.85
e	1.27 BSC		
G	0.51	0.575	0.71
K	1.20	1.35	1.50
L	0.51	0.575	0.71
L1	0.125 REF		
M	3.00	3.40	3.80
θ	0 °	---	12 °

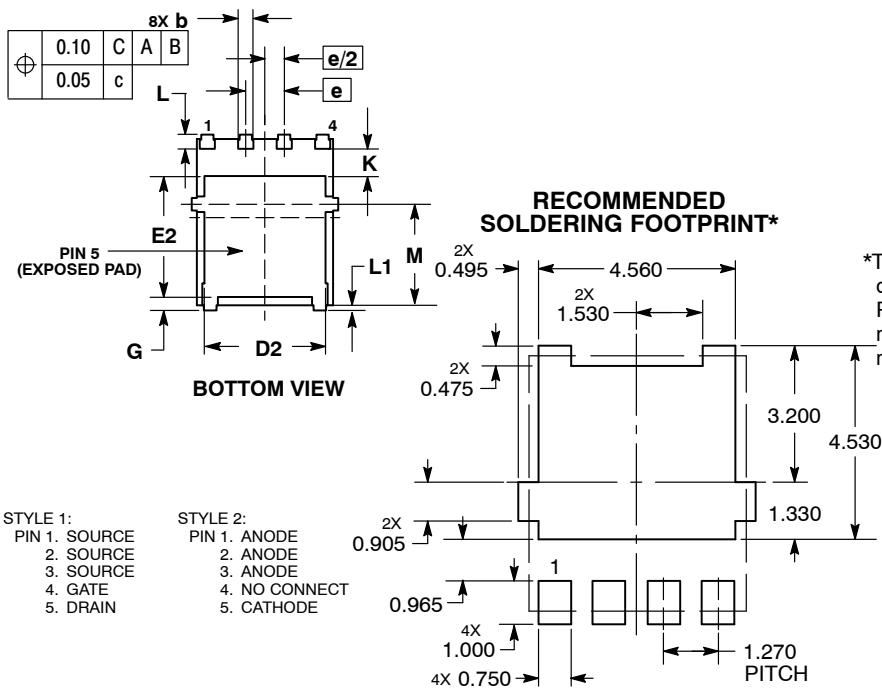


DETAIL A

SEATING PLANE



DETAIL A



STYLE 1:  
PIN 1. SOURCE  
2. SOURCE  
3. SOURCE  
4. GATE  
5. DRAIN

STYLE 2:  
PIN 1. ANODE  
2. ANODE  
3. ANODE  
4. NO CONNECT  
5. CATHODE

DIMENSIONS: MILLIMETERS

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	DFN5 5x6, 1.27P (SO-8FL)	PAGE 1 OF 1

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